Filename: PMP5568 - 350W PSU - MCU CARD REVB_bom.xls
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PMP5568 - 350W PSU - MCU CARD REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
2	C1, C2, C6, C11, C19, C22, C24, C26, C28, C5	100nF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
1	C101	1nF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
2	C12, C13	22uF	Capacitor, Ceramic, 6.3V, X5R, 15%	1210	Std	Std
8	C14, C15, C16, C17, C18, C23, C25, C27	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
2	C20, C21	10uF	Capacitor, Ceramic, 6.3V, X5R, 15%	0603	Std	Std
2	C3, C4	4.7uF	Capacitor, Ceramic, 25V, X5R, 15%	1206	Std	Std
1	C7	22pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C8	22nF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
2	C9, C10	open	Capacitor, Ceramic, 25V, X7R, 15%	0603	Std	Std
1	D1	MBRM120	Diode, Schottky, 1A, 20V	457-04	MBRM120E	On Semi
1	D2	MA2SD10	Diode, Schottky, 200mA, 20V	0.047 x 0.031 inch	MA2SD10	Panasonic
1	D3	Red	Diode, LED, THT, 3mm, red	T1-3/4	TLHR4400	Vishay
5	J2, J3, J4, J5, J10	PEC05SAAN	Header, Male 5-pin, 100mil spacing,	0.100 inch x 5	PEC05SAAN	Sullins
3	J6, J7, J8	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	J9	PEC10DAAN	Header, Female, 2x10-pin, 100mil spacing	0.100 inch x 10 x 2	SSW-110-01-T-D	Samtec
1	L1	4.7uH	Inductor, 0.7A	0.126 x 0.098 inch	VLF3010AT-4R7MR70	TDK
1	L2	100uH	Inductor, SMT, 253mOhm, 1.2A sat, 1.1A rms	0.402 x 0.394 inch	MSS1048-104ML	Coilcraft
1	Q1	BSS138	MOSFET, Nch, 50V, 0.22A, 3.5 Ohm	SOT23	BSS138	Fairchild
1	R1	82.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R10, R21, R25, R26	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R101	3.32k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
5	R13, R17, R18, R19, R20	681	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R14, R15, R16	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	20.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R22, R23, R24	100	Resistor, Chip, 1/4 watt, 1%	1206	Std	Std
7	R27, R28, R29, R30, R43, R45, R46	10.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	432k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R31	27.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R32	20k	Potentiometer, Single turn Cermet, Open-frame, 2mm SMT, Top-Adjust	0.087 x 0.108 inch	3302W-3-203E	Bourns
1	R33	22.1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R34	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std

1	R35	NTC	NTC, 100k, 5%	1206	NCP18WF104J03RB	muRata
1	R36	4.75k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R37, R38	1.00k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R4, R11, R12, R39	open	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R40, R44	5.11k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R41	25.5k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R42	33.2	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	29.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	5.62k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	34.8k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R9	open	Resistor, Chip, 1/16W, 1%	0805	Std	Std
4	S1, S2, S3, S4	B3J-2100	Switch, SPST NO Single LED 5VDC, 1mA	12x18 mm	B3J-2100	Omron
2	TP1, TP2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
11	TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20		Thru Hole, 15 mil, plated			
1	TP3	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	EADIP162	LCD MODULE, 2x16, 6.68mm	26.8 x 68.0mm	DIP162J-DN3LW	Electronic Assembly
1	U2	MSP430F2252RHA	IC, Mixed Signal Microcontroller	QFN-40	MSP430F2252RHA	Texas Instruments
1	U3	TPS54140DGQ	IC, DC-DC Converter With Eco-Mode, 1.5A, 42V	MSOP-10	TPS54140DGQ	Texas Instruments
1	U4	TPS715345DCKR	IC, High Input Voltage, Micropower	SOP-5 (DCK)	TPS715345DCKR	Texas Instruments

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